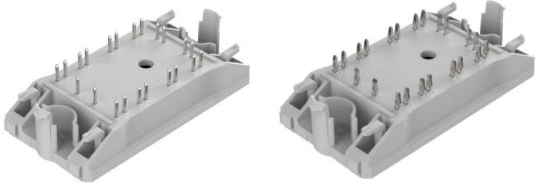
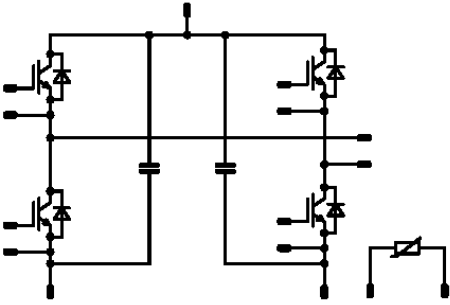




Vincotech

10-FZ074PA075SM-L625F08
10-PZ074PA075SM-L625F08Y
 datasheet

fast PACK 0 H C	650 V / 75 A
<div style="border: 1px solid black; padding: 5px; margin-bottom: 5px;"> <p style="text-align: center; background-color: #ccc; margin: 0;">Features</p> <ul style="list-style-type: none"> High speed H-Bridge High efficiency IGBT H5 Full current fast FWD Integrated capacitors Thermistor </div> <div style="border: 1px solid black; padding: 5px; margin-bottom: 5px;"> <p style="text-align: center; background-color: #ccc; margin: 0;">Target applications</p> <ul style="list-style-type: none"> Power Supply Solar Inverters UPS Welding & Cutting </div> <div style="border: 1px solid black; padding: 5px;"> <p style="text-align: center; background-color: #ccc; margin: 0;">Types</p> <ul style="list-style-type: none"> 10-FZ074PA075SM-L625F08 10-PZ074PA075SM-L625F08Y </div>	<div style="border: 1px solid black; padding: 5px; margin-bottom: 5px;"> <p style="text-align: center; background-color: #ccc; margin: 0;">flow 0 housing</p>  </div> <div style="border: 1px solid black; padding: 5px;"> <p style="text-align: center; background-color: #ccc; margin: 0;">Schematic</p>  </div>

Maximum Ratings

$T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
H-Bridge Switch				
Collector-emitter voltage	V_{CES}		650	V
Collector current	I_C	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	57	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	225	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	97	W
Gate-emitter voltage	V_{GES}		±20	V
Maximum Junction Temperature	T_{jmax}		175	°C



Maximum Ratings

$T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
-----------	--------	-----------	-------	------

H-Bridge Diode

Peak Repetitive Reverse Voltage	V_{RRM}		650	V
Continuous (direct) forward current	I_F	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	59	A
Repetitive peak forward current	I_{FRM}		150	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	78	W
Maximum Junction Temperature	T_{jmax}		175	°C

Capacitor (DC)

Maximum DC voltage	V_{MAX}		630	V
Operation Temperature	T_{op}		-55...+125	°C

Module Properties

Thermal Properties

Storage temperature	T_{stg}		-40...+125	°C
Operation temperature under switching condition	T_{jop}		-40...($T_{jmax} - 25$)	°C

Isolation Properties

Isolation voltage	V_{isol}	DC Test Voltage* $t_p = 2\text{ s}$	6000	V
		AC Voltage $t_p = 1\text{ min}$	2500	V
Creepage distance			min. 12,7	mm
Clearance		with solder pins / with press-fit pins	9,55 / 9,57	mm
Comparative Tracking Index	CTI		> 200	

*100 % tested in production



Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
		V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max		

H-Bridge Switch

Static

Gate-emitter threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{CE}$			0,00075	25	3,3	4	4,7	V
Collector-emitter saturation voltage	V_{CEsat}		15		75	25 125 150		1,67 1,84 1,89	2,22	V
Collector-emitter cut-off current	I_{CES}		0	650		25			40	μA
Gate-emitter leakage current	I_{GES}		20	0		25			120	nA
Internal gate resistance	r_g							none		Ω
Input capacitance	C_{ies}							4300		pF
Output capacitance	C_{oes}	$f = 1$ MHz	0	25		25		75		
Reverse transfer capacitance	C_{res}							16		
Gate charge	Q_g		15	520	75	25		166		nC

Thermal

Thermal resistance junction to sink	$R_{th(j-s)}$	phase-change material $\lambda = 3,4$ W/mK						0,98		K/W
-------------------------------------	---------------	---	--	--	--	--	--	------	--	-----

Dynamic

Turn-on delay time	$t_{d(on)}$					25 125 150		23 23 23		ns
Rise time	t_r	$R_{goff} = 4 \Omega$ $R_{gon} = 4 \Omega$				25 125 150		14 15 16		
Turn-off delay time	$t_{d(off)}$		15/0	350	75	25 125 150		116 131 135		
Fall time	t_f					25 125 150		4 8 10		
Turn-on energy (per pulse)	E_{on}	$Q_{tFWD} = 2,4 \mu C$ $Q_{tFWD} = 4,6 \mu C$ $Q_{tFWD} = 5,3 \mu C$				25 125 150		1,058 1,486 1,591		
Turn-off energy (per pulse)	E_{off}					25 125 150		0,277 0,481 0,527		



Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
		V_{GE} [V]	V_{CE} [V]	I_C [A]	T_j [°C]	Min	Typ	Max		

H-Bridge Diode

Static

Parameter	Symbol	V_{GS} [V]	V_{DS} [V]	I_D [A]	I_F [A]	T_j [°C]	Min	Typ	Max	Unit
Forward voltage	V_F			75		25 125 150		1,53 1,49 1,47	1,92	V
Reverse leakage current	I_r		650			25			3,8	µA

Thermal

Parameter	Symbol	Conditions	Value	Unit
Thermal resistance junction to sink	$R_{th(j-s)}$	phase-change material $\lambda = 3,4$ W/mK	1,23	K/W

Dynamic

Parameter	Symbol	dI/dt	V_{GS}	V_{DS}	I_D	T_j	Min	Typ	Max	Unit
Peak recovery current	I_{RRM}					25 125 150		51 69 74		A
Reverse recovery time	t_{rr}					25 125 150		84 109 123		ns
Recovered charge	Q_r	$dI/dt = 5120$ A/µs $dI/dt = 4804$ A/µs $dI/dt = 5399$ A/µs	15/0	350	75	25 125 150		2,383 4,616 5,343		µC
Reverse recovered energy	E_{rec}					25 125 150		0,511 1,036 1,222		mWs
Peak rate of fall of recovery current	$(di_{rr}/dt)_{max}$					25 125 150		750 682 570		A/µs

Capacitor (DC)

Parameter	Symbol	Conditions	Value	Unit	
Capacitance	C		150	nF	
Tolerance			-10	+10	%
Dissipation factor		$f = 1$ kHz		2,5	%

Thermistor

Parameter	Symbol	Conditions	Value	Unit		
Rated resistance	R		25	22	kΩ	
Deviation of R_{100}	$\Delta_{R/R}$	$R_{100} = 1484$ Ω	100	-5	5	%
Power dissipation	P		25	5	mW	
Power dissipation constant			25	1,5	mW/K	
B-value	$B_{(25/50)}$	Tol. ± 1 %	25	3962	K	
B-value	$B_{(25/100)}$	Tol. ± 1 %	25	4000	K	
Vincotech NTC Reference				I		

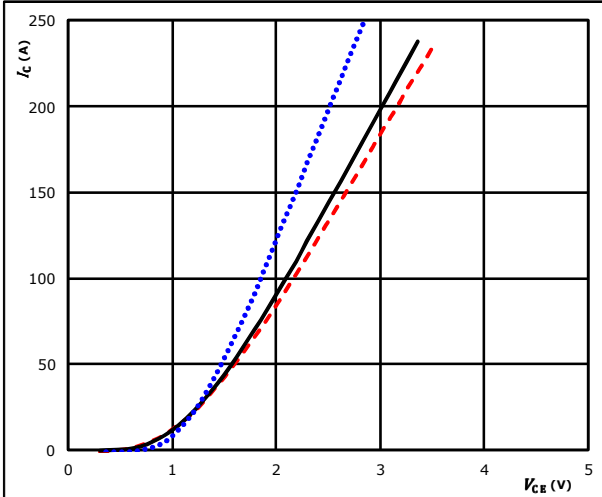


H-Bridge Switch Characteristics

figure 1. IGBT

Typical output characteristics

$I_C = f(V_{CE})$

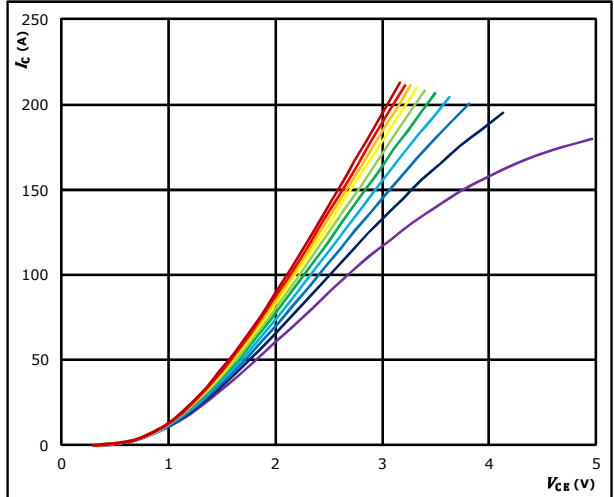


$t_p = 250 \mu s$
 $V_{GE} = 15 V$
 $T_j: 25 \text{ }^\circ C$ (dotted blue)
 $125 \text{ }^\circ C$ (solid black)
 $150 \text{ }^\circ C$ (dashed red)

figure 2. IGBT

Typical output characteristics

$I_C = f(V_{CE})$

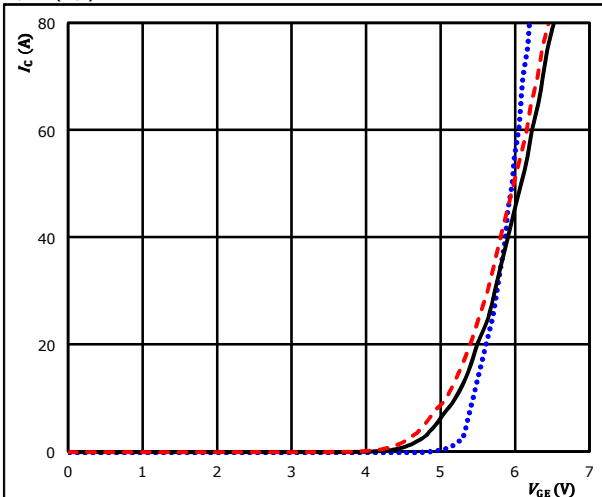


$t_p = 250 \mu s$
 $T_j = 150 \text{ }^\circ C$
 V_{GE} from 8 V to 17 V in steps of 1 V

figure 3. IGBT

Typical transfer characteristics

$I_C = f(V_{GE})$

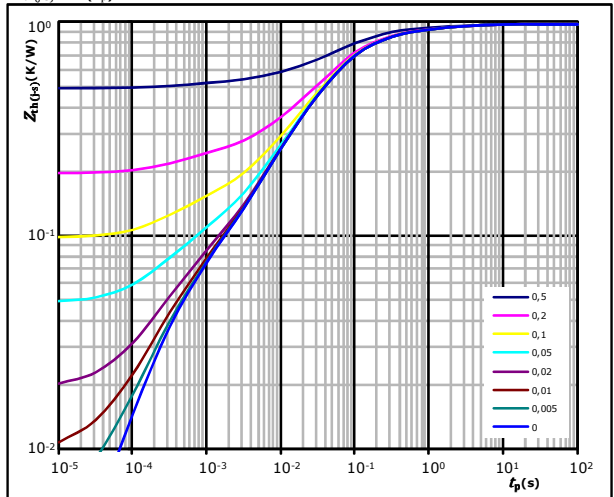


$t_p = 100 \mu s$
 $V_{CE} = 10 V$
 $T_j: 25 \text{ }^\circ C$ (dotted blue)
 $125 \text{ }^\circ C$ (solid black)
 $150 \text{ }^\circ C$ (dashed red)

figure 4. IGBT

Transient Thermal Impedance as function of Pulse duration

$Z_{th(j-s)} = f(t_p)$



$D = t_p / T$
 $R_{th(j-s)} = 0,98 \text{ K/W}$

IGBT thermal model values

R (K/W)	τ (s)
7,21E-02	2,25E+00
1,46E-01	3,32E-01
4,74E-01	6,42E-02
1,76E-01	1,63E-02
6,17E-02	3,99E-03
4,63E-02	3,57E-04

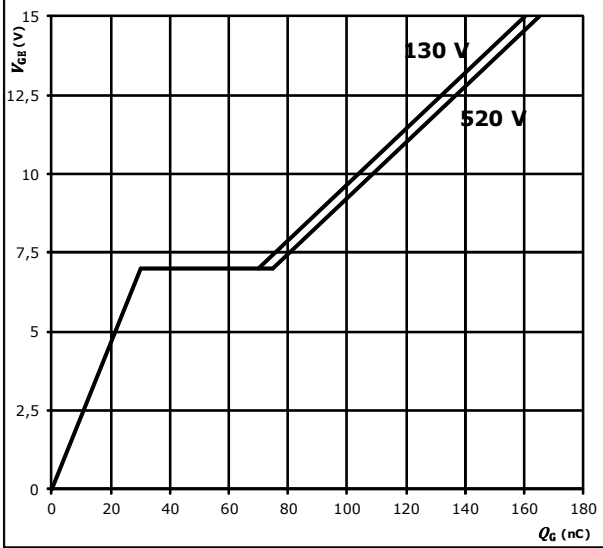


H-Bridge Switch Characteristics

figure 5. IGBT

Gate voltage vs Gate charge

$V_{GE} = f(Q_G)$



At

I_C = 75 A

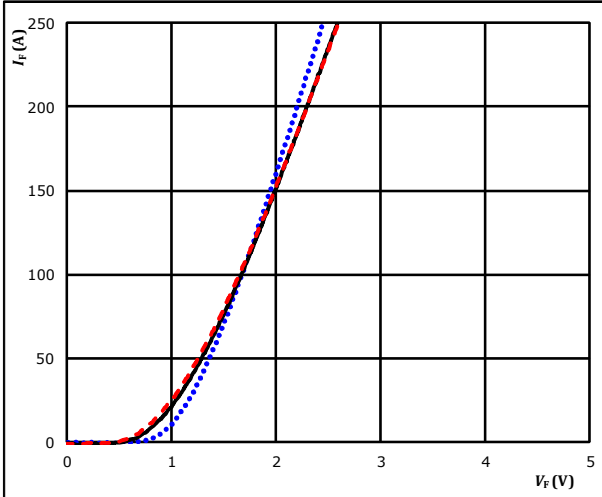


H-Bridge Diode Characteristics

figure 1. FWD

Typical forward characteristics

$I_F = f(V_F)$

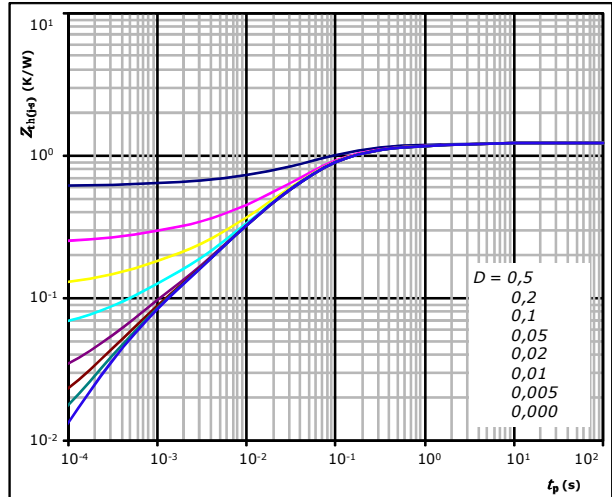


$t_p = 250 \mu s$
 T_j : 25 °C (dotted blue), 125 °C (solid black), 150 °C (dashed red)

figure 2. FWD

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



$D = t_p / T$
 $R_{th(j-s)} = 1,23 \text{ K/W}$

FWD thermal model values

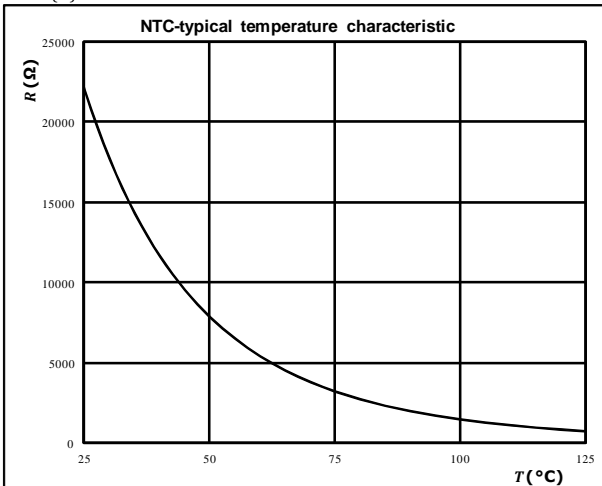
R (K/W)	τ (s)
8,04E-02	2,68E+00
1,74E-01	2,85E-01
6,28E-01	6,23E-02
2,05E-01	1,65E-02
8,90E-02	4,15E-03
4,76E-02	4,96E-04

Thermistor Characteristics

figure 1. Thermistor

Typical NTC characteristic as a function of temperature

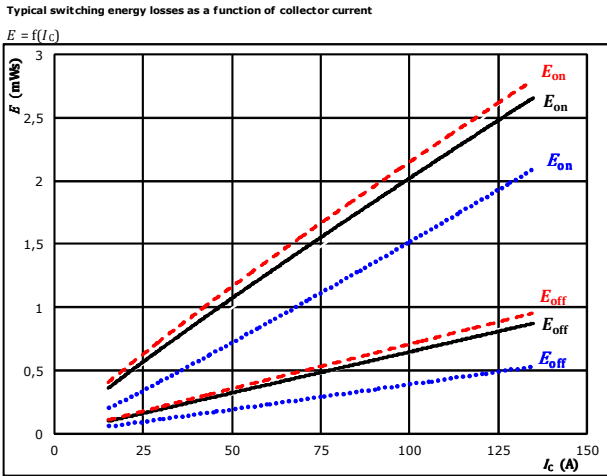
$R = f(T)$





Switching Characteristics

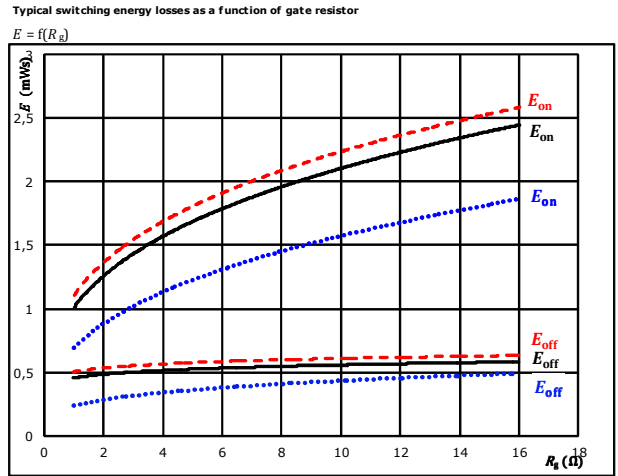
figure 1. IGBT



With an inductive load at

$V_{CE} = 350$ V	$T_j: 25$ °C
$V_{GE} = 15/0$ V	$T_j: 125$ °C	————
$R_{gon} = 4$ Ω	$T_j: 150$ °C	-----
$R_{goff} = 4$ Ω		

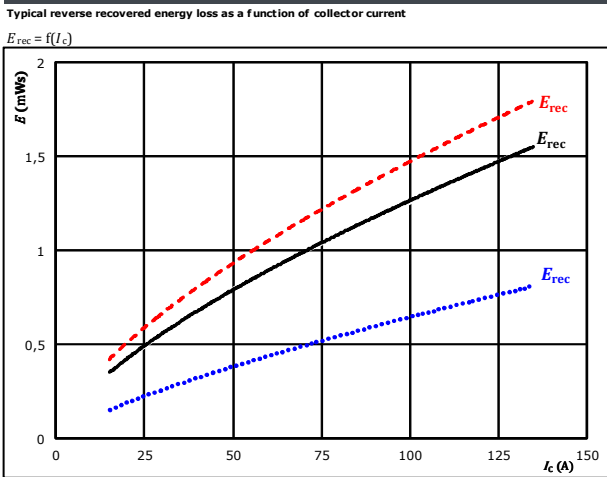
figure 2. IGBT



With an inductive load at

$V_{CE} = 350$ V	$T_j: 25$ °C
$V_{GE} = 15/0$ V	$T_j: 125$ °C	————
$I_c = 75$ A	$T_j: 150$ °C	-----

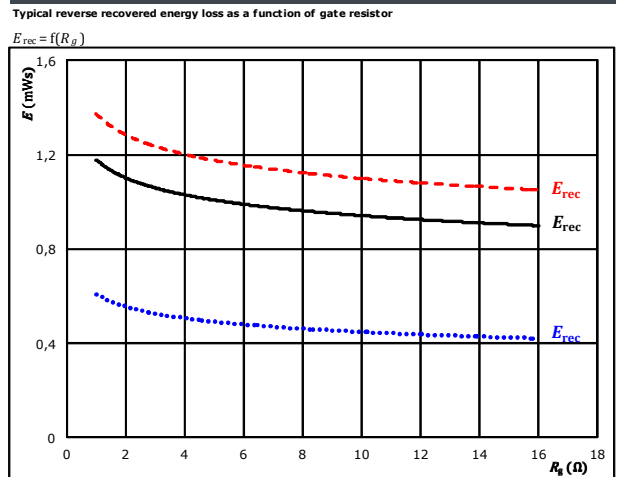
figure 3. FWD



With an inductive load at

$V_{CE} = 350$ V	$T_j: 25$ °C
$V_{GE} = 15/0$ V	$T_j: 125$ °C	————
$R_{gon} = 4$ Ω	$T_j: 150$ °C	-----

figure 4. FWD



With an inductive load at

$V_{CE} = 350$ V	$T_j: 25$ °C
$V_{GE} = 15/0$ V	$T_j: 125$ °C	————
$I_c = 75$ A	$T_j: 150$ °C	-----

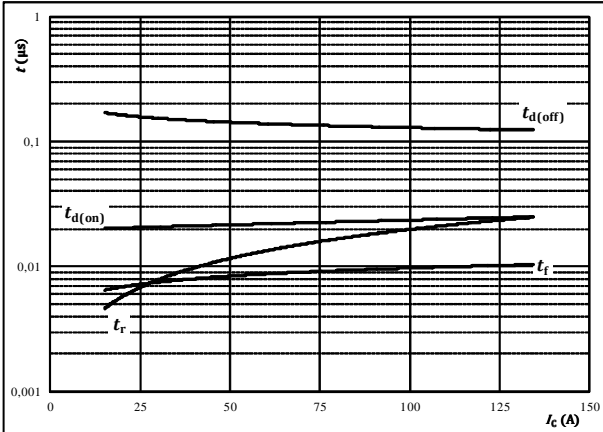


Switching Characteristics

figure 5. IGBT

Typical switching times as a function of collector current

$$t = f(I_C)$$



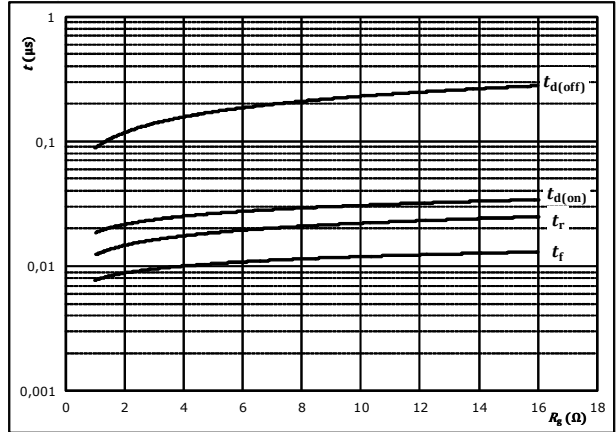
With an inductive load at

$T_j =$	150	°C
$V_{CE} =$	350	V
$V_{GE} =$	15/0	V
$R_{gon} =$	4	Ω
$R_{goff} =$	4	Ω

figure 6. IGBT

Typical switching times as a function of gate resistor

$$t = f(R_g)$$



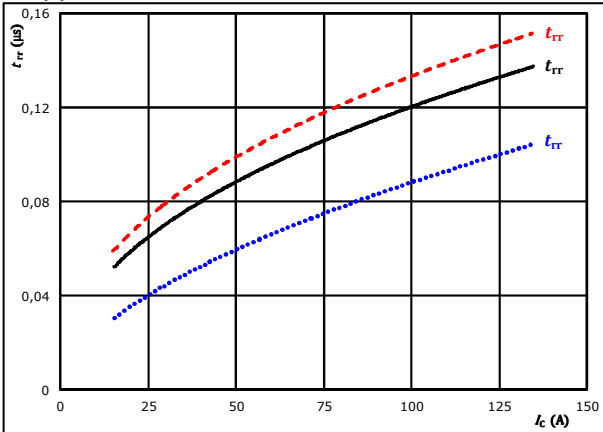
With an inductive load at

$T_j =$	150	°C
$V_{CE} =$	350	V
$V_{GE} =$	15/0	V
$I_C =$	75	A

figure 7. FWD

Typical reverse recovery time as a function of collector current

$$t_{rr} = f(I_C)$$

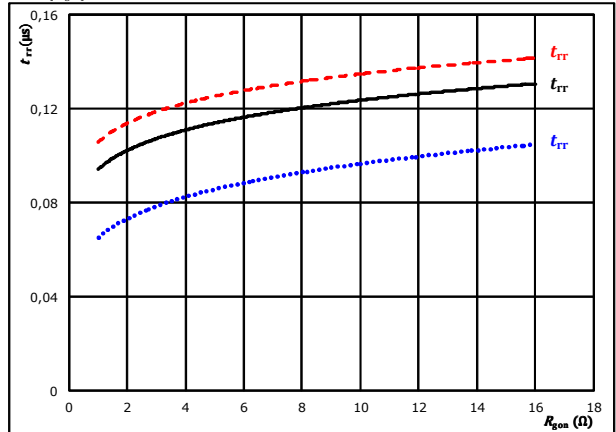


At	$V_{CE} =$	350	V	$T_j:$	25 °C
	$V_{GE} =$	15/0	V		125 °C	————
	$R_{gon} =$	4	Ω		150 °C	-----

figure 8. FWD

Typical reverse recovery time as a function of IGBT turn on gate resistor

$$t_{rr} = f(R_{gon})$$



At	$V_{CE} =$	350	V	$T_j:$	25 °C
	$V_{GE} =$	15/0	V		125 °C	————
	$I_C =$	75	A		150 °C	-----

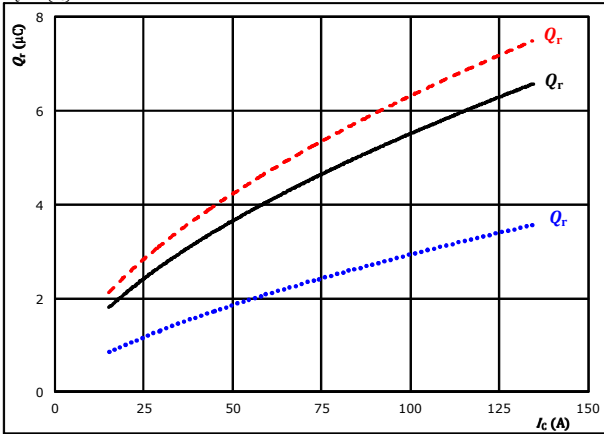


Switching Characteristics

figure 9. FWD

Typical recovered charge as a function of collector current

$$Q_r = f(I_c)$$

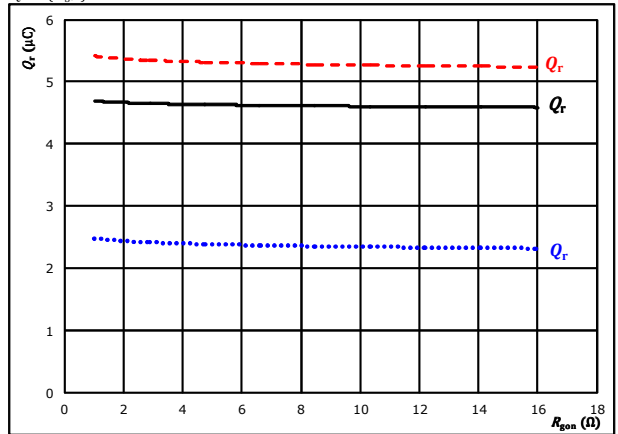


At $V_{CE} = 350$ V $T_j: 25$ °C
 $V_{GE} = 15/0$ V $T_j: 125$ °C ———
 $R_{gpn} = 4$ Ω $T_j: 150$ °C - - - - -

figure 10. FWD

Typical recovered charge as a function of IGBT turn on gate resistor

$$Q_r = f(R_{gpn})$$

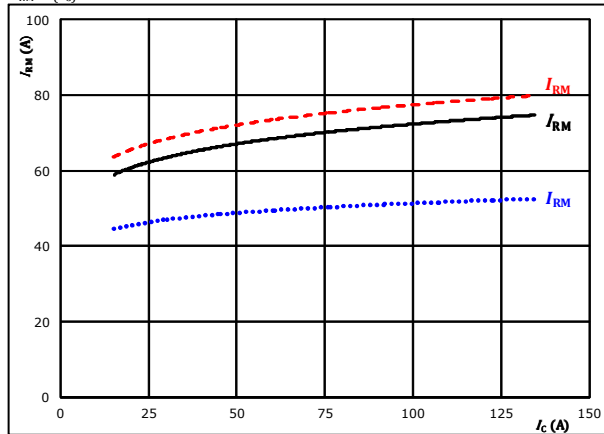


At $V_{CE} = 350$ V $T_j: 25$ °C
 $V_{GE} = 15/0$ V $T_j: 125$ °C ———
 $I_c = 75$ A $T_j: 150$ °C - - - - -

figure 11. FWD

Typical peak reverse recovery current current as a function of collector current

$$I_{RM} = f(I_c)$$

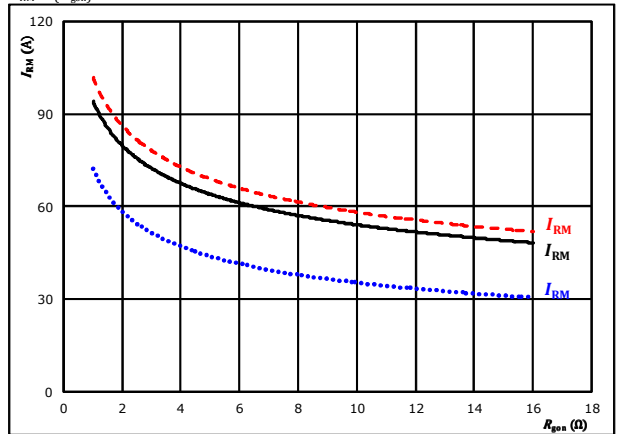


At $V_{CE} = 350$ V $T_j: 25$ °C
 $V_{GE} = 15/0$ V $T_j: 125$ °C ———
 $R_{gpn} = 4$ Ω $T_j: 150$ °C - - - - -

figure 12. FWD

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

$$I_{RM} = f(R_{gpn})$$



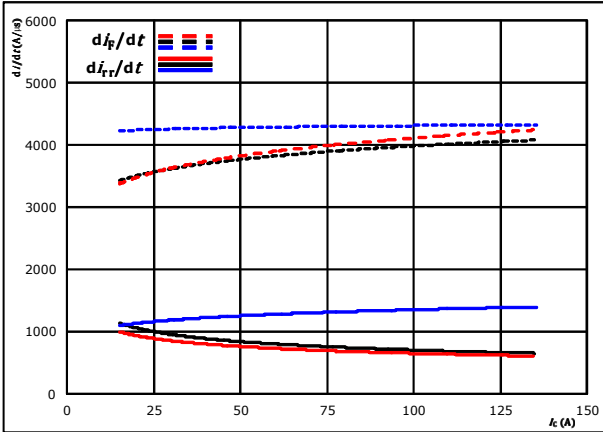
At $V_{CE} = 350$ V $T_j: 25$ °C
 $V_{GE} = 15/0$ V $T_j: 125$ °C ———
 $I_c = 75$ A $T_j: 150$ °C - - - - -



Switching Characteristics

figure 13. FWD

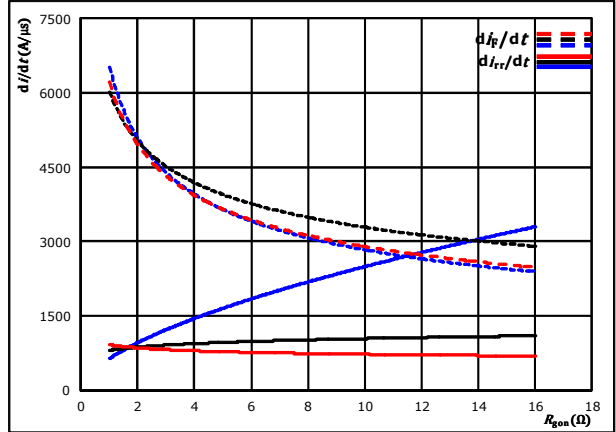
Typical rate of fall of forward and reverse recovery current as a function of collector current
 $di_f/dt, di_{rr}/dt = f(I_c)$



At $V_{CE} = 350$ V $T_j = 25$ °C
 $V_{GE} = 15/0$ V $T_j = 125$ °C ———
 $R_{gon} = 4$ Ω $T_j = 150$ °C - - - - -
 $T_j = 175$ °C - · - · - ·

figure 14. FWD

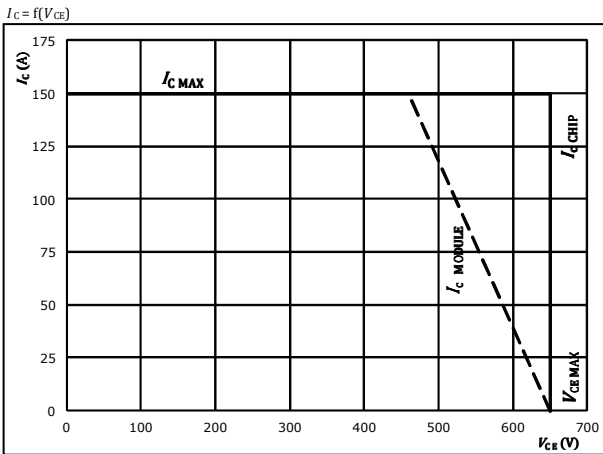
Typical rate of fall of forward and reverse recovery current as a function of IGBT turn on gate resistor
 $di_f/dt, di_{rr}/dt = f(R_{gon})$



At $V_{CE} = 350$ V $T_j = 25$ °C
 $V_{GE} = 15/0$ V $T_j = 125$ °C ———
 $I_c = 75$ A $T_j = 150$ °C - - - - -
 $T_j = 175$ °C - · - · - ·

figure 15. IGBT

Reverse bias safe operating area



At $T_j = 175$ °C
 $R_{gon} = 4$ Ω
 $R_{goff} = 4$ Ω

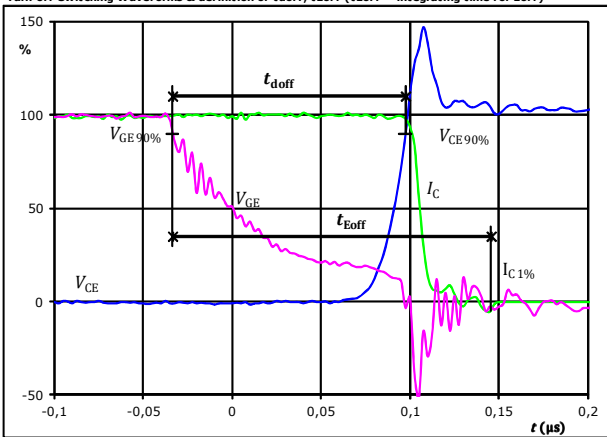


Switching Definitions

General conditions

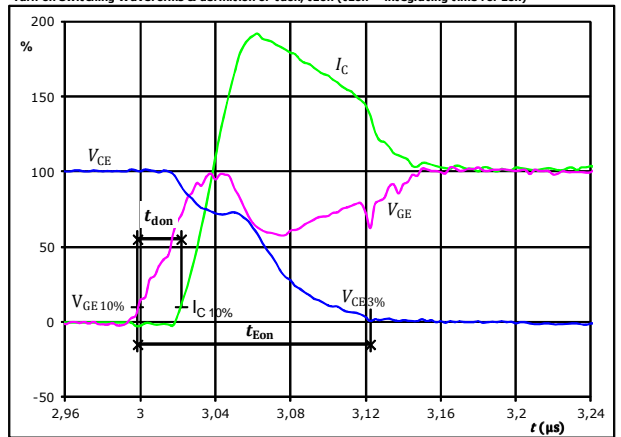
T_j	=	125 °C
R_{gon}	=	4 Ω
R_{goff}	=	4 Ω

figure 1. IGBT
 Turn-off Switching Waveforms & definition of t_{doff} , t_{Eoff} (t_{Eoff} = integrating time for E_{off})



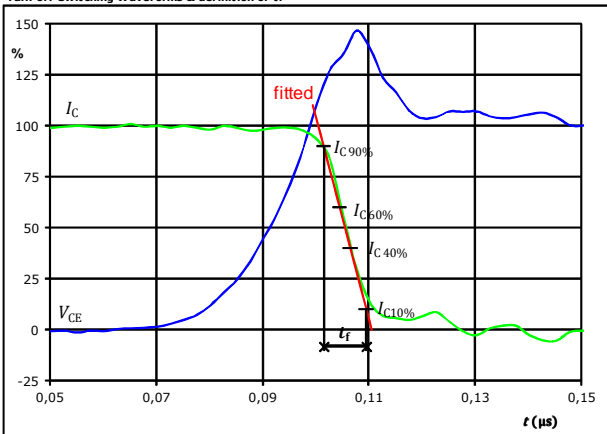
$V_{GE}(0\%) =$	0	V
$V_{GE}(100\%) =$	15	V
$V_C(100\%) =$	350	V
$I_C(100\%) =$	75	A
$t_{doff} =$	0,131	μs
$t_{Eoff} =$	0,179	μs

figure 2. IGBT
 Turn-on Switching Waveforms & definition of t_{don} , t_{Eon} (t_{Eon} = integrating time for E_{on})



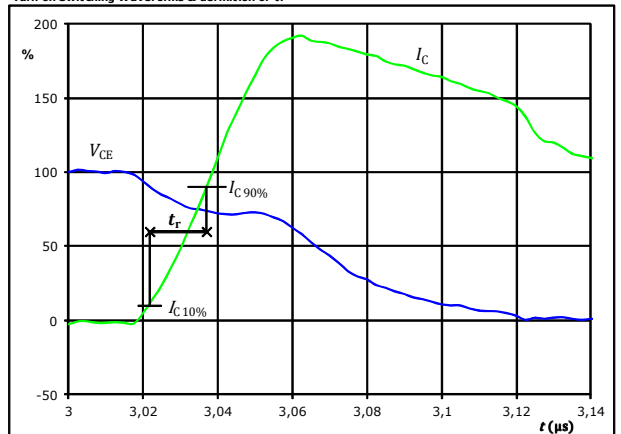
$V_{GE}(0\%) =$	0	V
$V_{GE}(100\%) =$	15	V
$V_C(100\%) =$	350	V
$I_C(100\%) =$	75	A
$t_{don} =$	0,023	μs
$t_{Eon} =$	0,124	μs

figure 3. IGBT
 Turn-off Switching Waveforms & definition of t_f



$V_C(100\%) =$	350	V
$I_C(100\%) =$	75	A
$t_f =$	0,008	μs

figure 4. IGBT
 Turn-on Switching Waveforms & definition of t_r



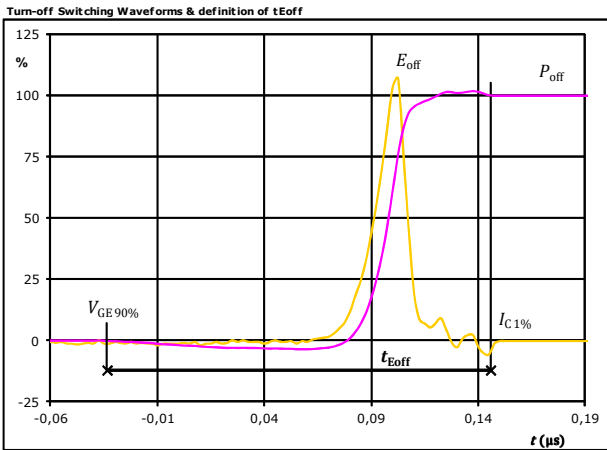
$V_C(100\%) =$	350	V
$I_C(100\%) =$	75	A
$t_r =$	0,015	μs



Vincotech

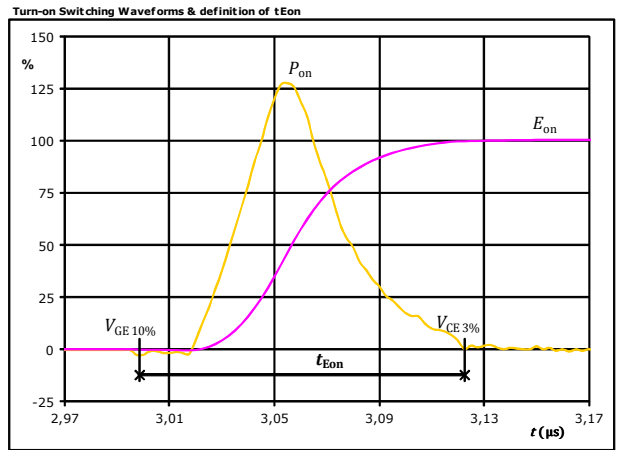
Switching Characteristics

figure 5. IGBT



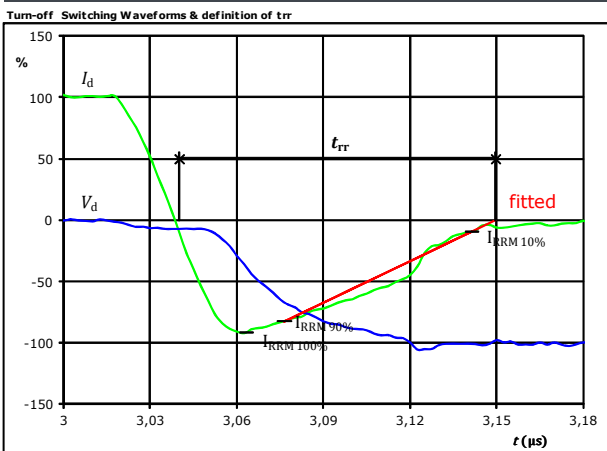
$P_{off}(100\%) = 26,34$ kW
 $E_{off}(100\%) = 0,48$ mJ
 $t_{Eoff} = 0,18$ μ s

figure 6. IGBT



$P_{on}(100\%) = 26,34$ kW
 $E_{on}(100\%) = 1,49$ mJ
 $t_{Eon} = 0,12$ μ s

figure 7. FWD

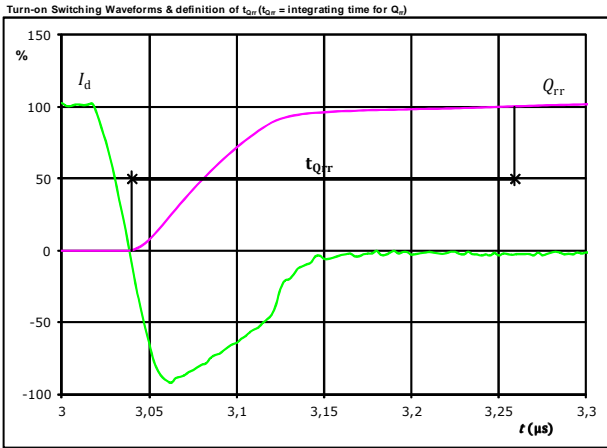


$V_d(100\%) = 350$ V
 $I_d(100\%) = 75$ A
 $I_{RRM}(100\%) = -69$ A
 $t_{Eoff} = 0,109$ μ s



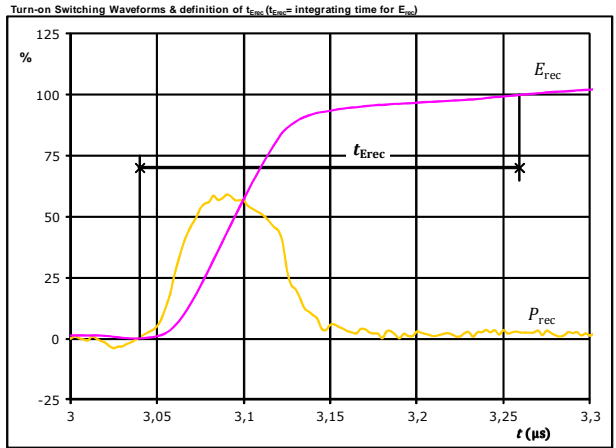
Switching Characteristics

figure 8. FWD



I_d (100%) =	75	A
Q_{rr} (100%) =	4,62	μC
t_{Qrr} =	0,22	μs

figure 9. FWD



P_{rec} (100%) =	26,34	kW
E_{rec} (100%) =	1,04	mJ
t_{Erec} =	0,22	μs



10-FZ074PA075SM-L625F08
10-PZ074PA075SM-L625F08Y
 datasheet

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Ordering Code & Marking								
Version				Ordering Code				
without thermal paste 12 mm housing with solder pins				10-FZ074PA075SM-L625F08				
without thermal paste 12 mm housing with press-fit pins				10-PZ074PA075SM-L625F08Y				
NN-NNNNNNNNNNNN TTTTWW WWYY UL VIN LLLL SSSS			Text	Name	Date code	UL & VIN	Lot	Serial
			Datamatrix	Type&Ver	Lot number	Serial	Date code	
				NN-NNNNNNNNNNNN-TTTTWW	WWYY	UL VIN	LLLLL	SSSS
				TTTTTWW	LLLLL	SSSS	WWYY	

Pin table [mm]			
Pin	X	Y	Function
1	0	22,5	G11
2	2,9	22,5	S11
3	8,3	22,5	DC-1
4	10,8	22,5	DC-1
5	19,6	22,5	DC+
6	22,1	22,5	DC+
7	29,1	22,5	S12
8	32	22,5	G12
9	33,5	17,8	Ph1
10	33,5	15,3	Ph1
11	33,5	7,2	Ph2
12	33,5	4,7	Ph2
13	32	0	G14
14	29,1	0	S14
15	22,1	0	DC+
16	19,6	0	DC+
17	10,8	0	DC-2
18	8,3	0	DC-2
19	2,9	0	S13
20	0	0	G13
21	0	8	Therm1
22	0	14,5	Therm2

Outline

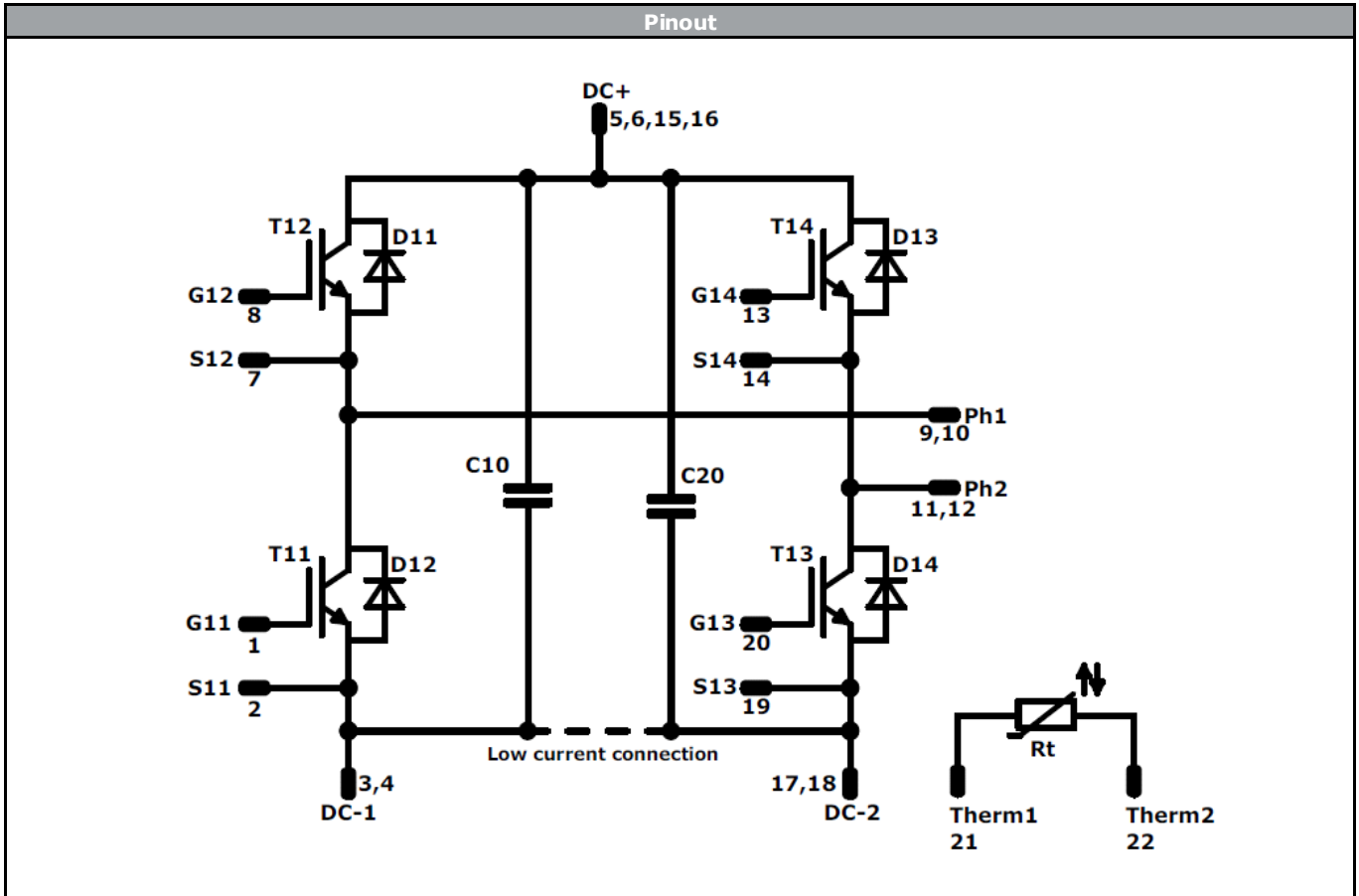
Tolerance of pinpositions ±0.5mm at the end of pins
 Dimension of coordinate axis is only offset without tolerance

center of press-fit pinhead
 for connection parameter see the handling instruction

Tolerance of pinpositions ±0.5mm at the end of pins
 Dimension of coordinate axis is only offset without tolerance



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Identification					
ID	Component	Voltage	Current	Function	Comment
T11-T14	IGBT	650 V	75 A	H-Bridge Switch	
D11-D14	FWD	650 V	75 A	H-Bridge Diode	
C10, C20	Capacitor	630 V		Capacitor (DC)	
Rt	Thermistor			Thermistor	




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Packaging instruction			
Standard packaging quantity (SPQ) 135	>SPQ	Standard	<SPQ Sample

Handling instruction
Handling instructions for <i>flow 0</i> packages see vincotech.com website.

Package data
Package data for <i>flow 0</i> packages see vincotech.com website.

UL recognition and file number
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website. 

Document No.:	Date:	Modification:	Pages
10-xZ074PA075SM-L625F08x-D1-14	30 May. 2017		

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.